

Electronic Patent Application Fee Transmittal

Application Number:	10565259			
Filing Date:				
Title of Invention:	Support With Solder Ball Elements and a Method for Populating Substrates With Solder Balls			
First Named Inventor:	Michael Bauer			
Filer:	Steven Edward Dicke/Ursula Weeks			
Attorney Docket Number:	1431145101FIN606PCTUS			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Independent claims in excess of 3	1614	1	200	200
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				200